

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Akihiko ENDO	06/06/2008
Nobuyuki MORIMOTO	06/06/2008
RECEIVING PARTY DATA	
Name:	SUMCO CORPORATION
Street Address:	2-1, Shibaura 1-chome, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	105-8634
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12057896
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NAME OF SUBMITTER:	Daniel B. Moon
Total Attachments: 3 source=P34200_Assignment#page1.tif source=P34200_Assignment#page2.tif source=P34200_Assignment#page3.tif	

OP \$40.00 12057896

**PATENT**

**500563922**

**REEL: 021080 FRAME: 0890**

ASSIGNMENT

WHEREAS, **Akihiko ENDO**, a citizen of Japan, whose post office address is c/o SUMCO Corporation, 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634 Japan, and **Nobuyuki MORIMOTO**, a citizen of Japan, whose post office address is SUMCO Corporation, 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634 Japan, hereinafter referred to as the ASSIGNORS, have invented a certain improvement relating to

**METHOD OF MANUFACTURING BONDED WAFER**

for which they have jointly executed an application for Letters Patent of the United States to be filed in the United States Patent and Trademark Office.

If this Assignment is filed after the filing date of the above-identified application, the undersigned hereby authorize and request any one of the attorneys of record in this application including Neil F. Greenblum, Reg. No. 28,394, Bruce H. Bernstein, Reg. No. 29,027, Arnold Turk, Reg. No. 33,094, James L. Rowland, Reg. No. 32,674, Stephen M. Roylance, Reg. No. 31,296, Leslie J. Paperner, Reg. No. 33,329, William Pieprz, Reg. No. 33,630, Robert W. Mueller, Reg. No. 35,043, William E. Lyddane, Reg. No. 41,568 and William S. Boshnick, Reg. No. 44,550, of the firm Greenblum & Bernstein, P.L.C., whose address is 1950 Roland Clarke Place, Reston, Virginia 20191, to insert here in parenthesis (Application No. 12/057,896, filed 03/28/2008) the filing date and application number of said application when known.

AND WHEREAS, **SUMCO Corporation**, a corporation organized and existing under the laws of Japan, whose post-office address is 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634 Japan, hereinafter known as the ASSIGNEE, is desirous of acquiring the entire right, title and interest for the United States and elsewhere throughout the world in and to said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, reexaminations, and prolongations thereof.

NOW, THIS WITNESSETH that for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt whereof is hereby acknowledged, said ASSIGNORS hereby assign, sell and transfer to said ASSIGNEE, its assigns and legal representatives, the entire and exclusive right, title and interest in and to said invention and application, for the United States and elsewhere throughout the world including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted therefor and all rights to sue for past and future infringement thereunder, said ASSIGNEE and its assigns and legal representatives to have, hold, exercise and enjoy the said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, reexaminations and prolongations thereof, with all the rights, powers, privileges, and advantages in any ways arising from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when granted, including any and all renewals, reissues, reexaminations, and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives in as ample and beneficial a manner to all intents and purposes as

the said ASSIGNORS might or could have held and enjoyed the same, if this assignment had not been made.

AND said ASSIGNORS hereby agree to execute all papers necessary to file applications in the United States and elsewhere throughout the world for said invention and to assign the same to said ASSIGNEE, or any assignee acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing Letters Patent thereon.

AND said ASSIGNORS authorize and request the Commissioner of Patents to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

IN TESTIMONY WHEREOF, this assignment is executed on the respective date(s) indicated below.

First Witness:

*Hideki Nishihata*  
(Name) Hideki NISHIHATA

June 6, 2008  
(Date)

*Akihiko Endo* June 6, 2008  
Akihiko ENDO Date

Second Witness:

*Daisuke Kikuchi*  
(Name) Daisuke KIKUCHI

June 6, 2008  
(Date)

First Witness:

Hideki Nishihata  
(Name) Hideki NISHIHATA

June 6, 2008  
(Date)

Nobuyuki Morimoto June 6, 2008  
Nobuyuki MORIMOTO Date

Second Witness:

Daisuke Kikuchi  
(Name) Daisuke KIKUCHI

June 6, 2008  
(Date)

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